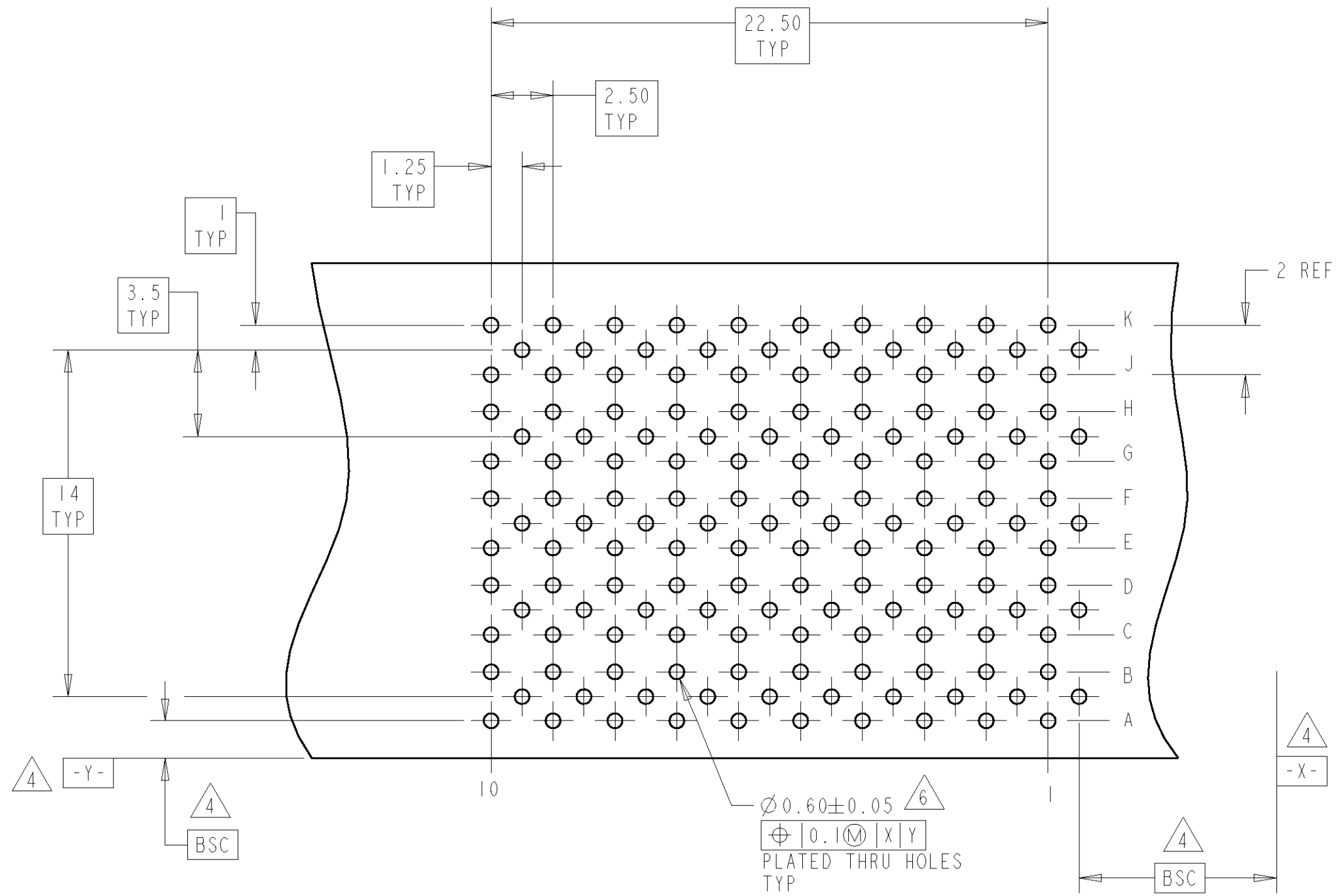
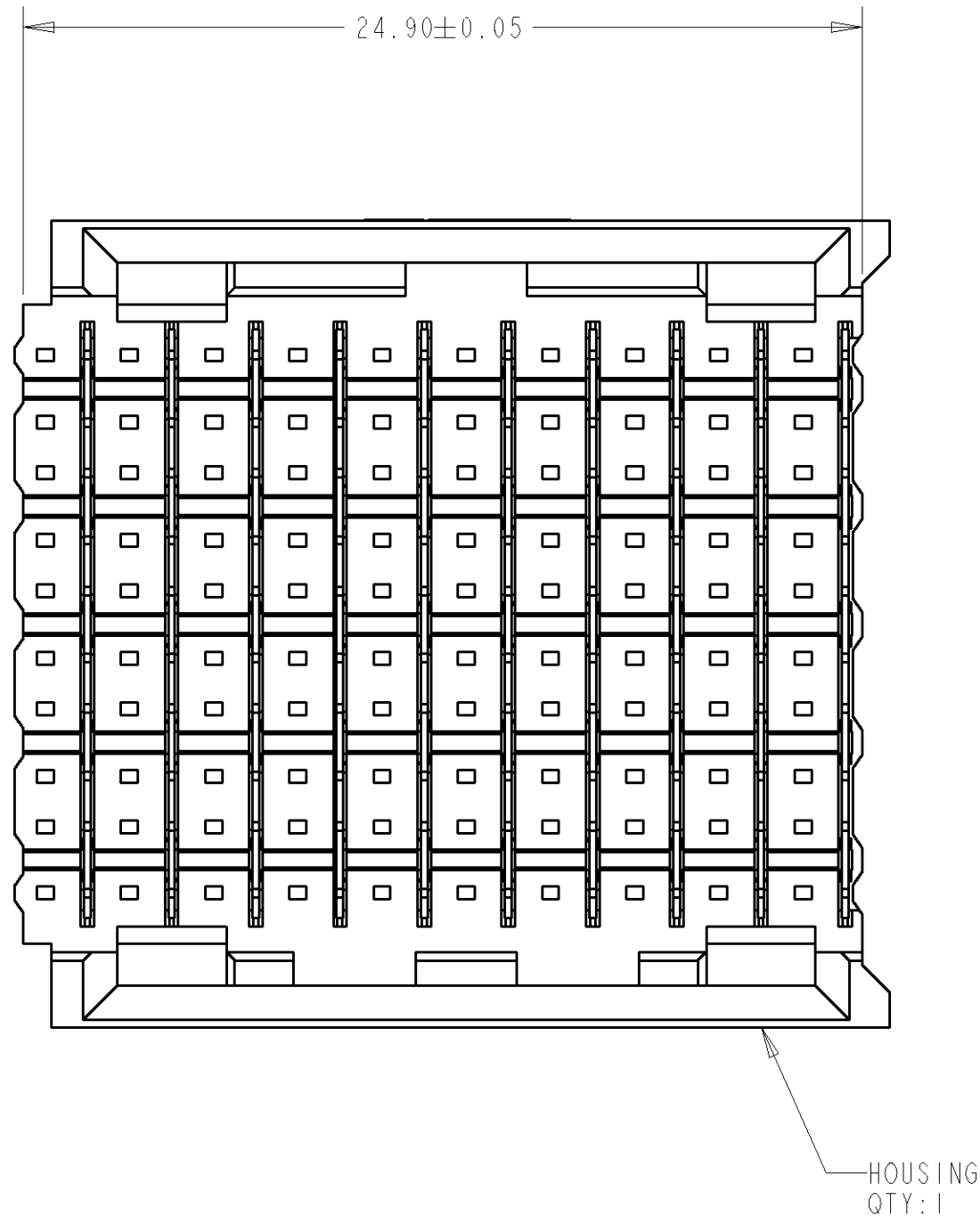
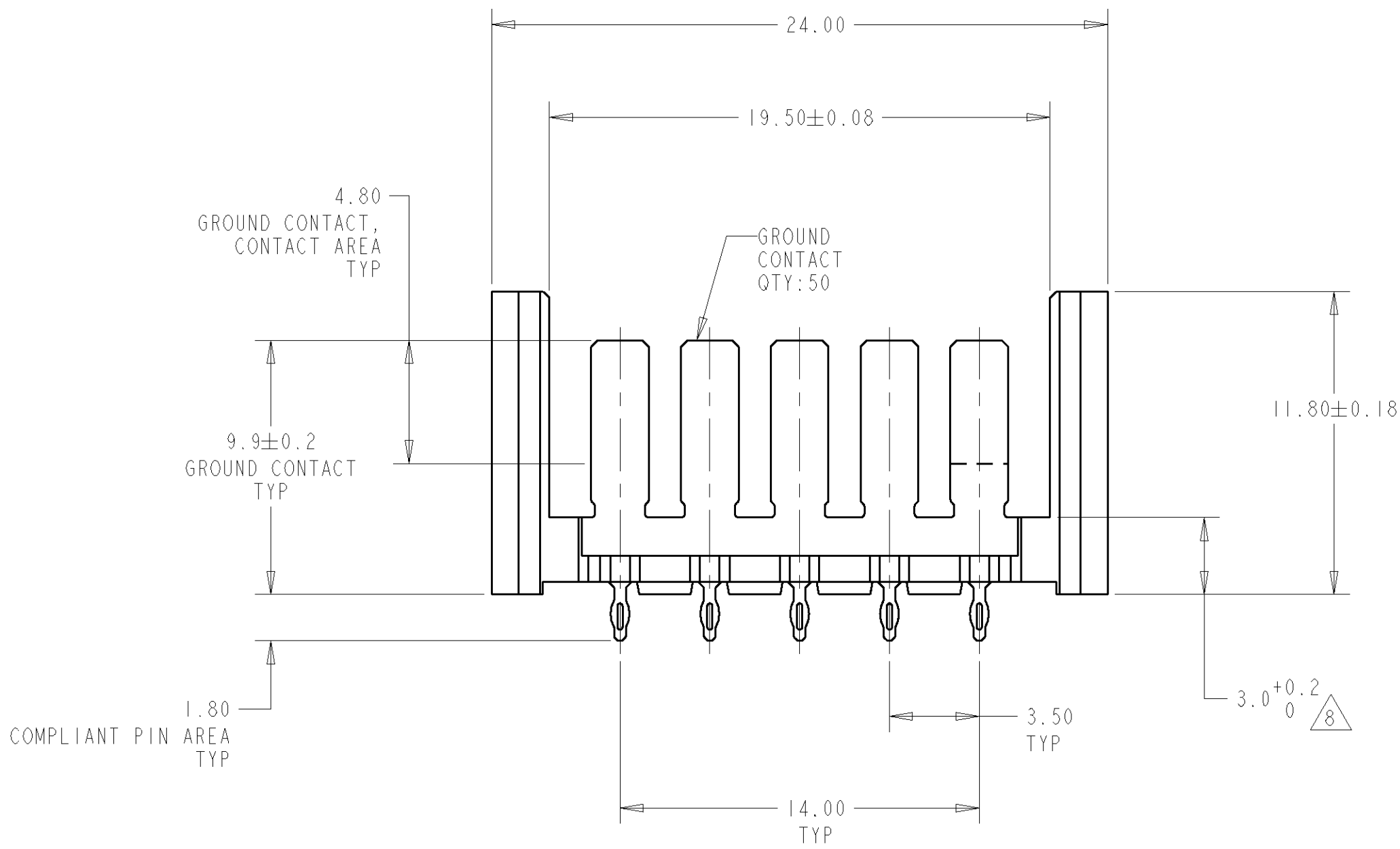
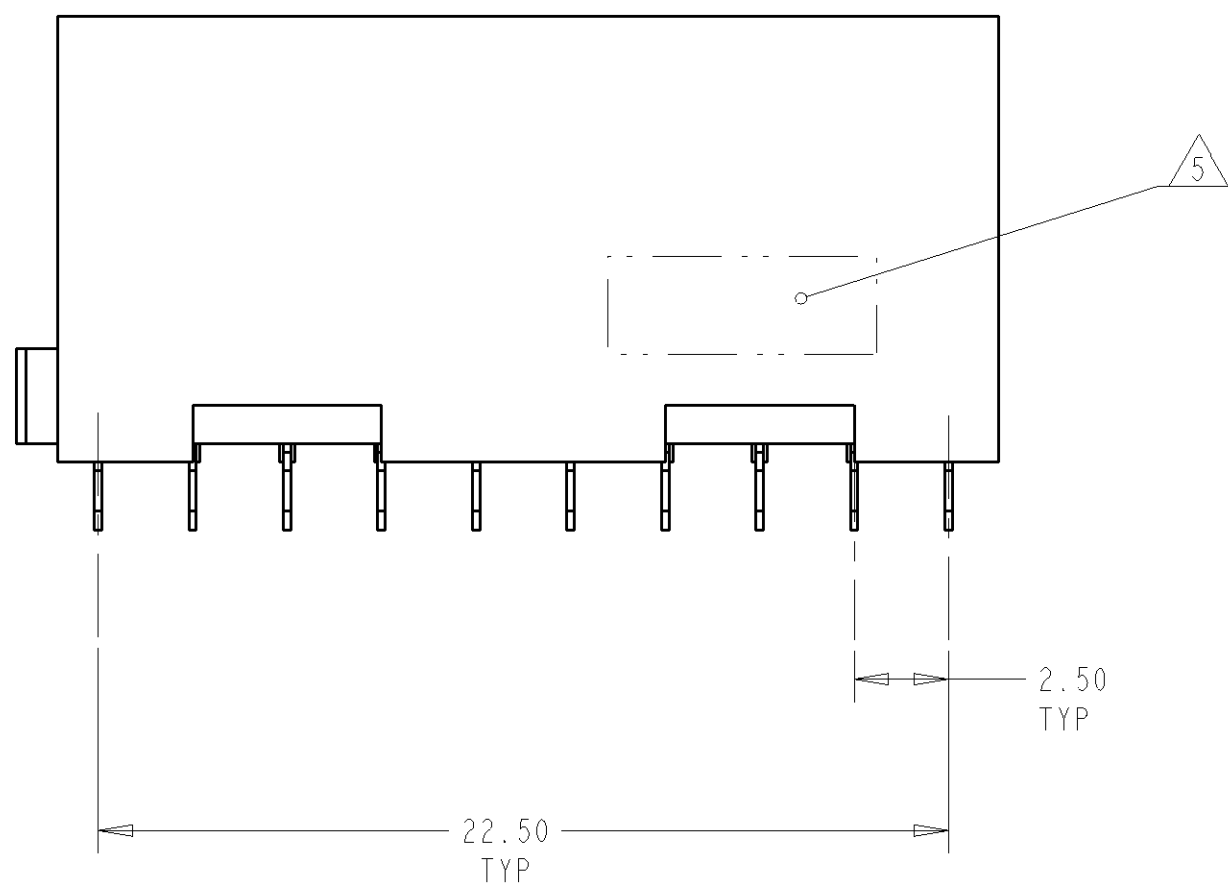


LOC	DIST	REVISIONS					
AD	47	REV	LTR	DESCRIPTION	DATE	DWN	APPD
			O	RELEASED PER 001B-0148-99 WAS 97-8159-44	110CT99	DKS	HWA
			A	REVISED PER 001B-0078-01	08MAY01	DKS	RAP
			-	-	-	-	-
			-	-	-	-	-

- | | |
|---|---|
| 1 | GOLD FLASH OVER 0.76µm MIN PALLADIUM NICKEL OVER 1.27µm MIN NICKEL ON CONTACT AREA
0.5µm MIN TIN LEAD OVER 1.27µm MIN NICKEL ON COMPLIANT PIN AREA |
| 2 | PHOSPHOR BRONZE |
| 3 | GLASS FILLED POLYESTER |
| 4 | DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER |
| 5 | CONNECTOR MARKED WITH PART NUMBER AND DATE CODE |
| 6 | DRILLED HOLE DIAMETER 0.7±0.025
FINISHED HOLE DIA 0.60±0.05 REF
COPPER THICKNESS 0.025-0.050
TIN LEAD THICKNESS 0.004-0.010 |
| 7 | CONTACT AREA LUBRICATED WITH BELLCORE APPROVED LUBRICANT
TECHNICAL REFERENCE: GR-1217-CORE, ISSUE 1, NOVEMBER 1995 |
| 8 | APPLICATION SEATING HEIGHT TO PRINTED CIRCUIT BOARD |



RECOMMENDED
PRINTED CIRCUIT BOARD
LAYOUT
COMPONENT SIDE OF PRINTED CIRCUIT BOARD



THIS DRAWING IS A CONTROLLED DOCUMENT FOR THE ELECTRONIC CORPORATION ANY REVISIONS TO THIS DRAWING MUST BE APPROVED BY THE ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		DWN H. MOLL 11JAN99				Tyco Electronics Harrisburg, PA 17105-3608	
DIMENSIONS : mm		TOLERANCES, UNLESS OTHERWISE SPECIFIED : 0 P L C ± 2 P L C ±0.13 3 P L C ± 4 P L C ± ANGLES ±°		CHK S. MICKIEWICZ 28JUN99		NAME SHROUD ASSEMBLY, 100 POSITION, 10 ROW, BACKPLANE CONNECTOR, Z-PACK HS3	
		APVD H. ANDREWS 28JUN99		PRODUCT SPEC - APPLICATION SPEC -		SIZE A	
MATERIAL HOUSING : 3 CONTACTS : 2		FINISH GROUND CONTACT : 1		WEIGHT -		DRAWING NO 00779 C=120663	
CUSTOMER DRAWING				SCALE 5:1		SHEET 1 OF 1 REV A	